

IR-1837 (2-2841)

TITLE: BACK-TO-BACK CONNECTED POWER
SEMICONDUCTOR DEVICE PACKAGE

ABSTRACT OF THE DISCLOSURE

A small footprint package for two or more semiconductor die includes first and second die, mounted on opposite respective surfaces of a lead frame pad in vertical alignment with one another. A conductive or insulation adhesive can be used. The die can be identical MOSgated devices connected in series, or can be one power die and a second IC die for the control of the power die.

20510" 2005002 011502